

# LN66F

## GaAs Infrared Light Emitting Diode

For remote control systems

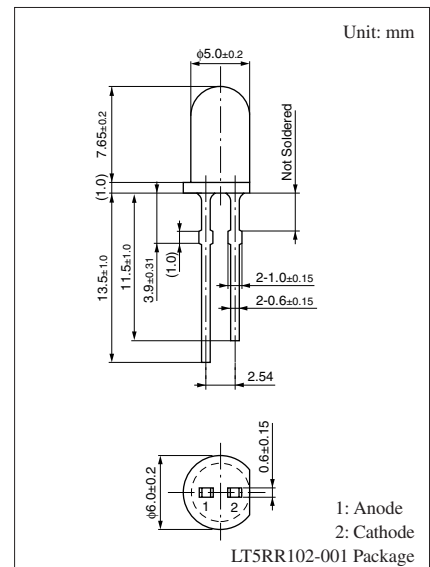
### ■ Features

- High-power output, high-efficiency:  $I_e = 13.0 \text{ mW/sr (min.)}$
- Emitted light spectrum suited for silicon photodetectors
- Narrow directivity:  $\theta = 15^\circ \text{ (typ.)}$
- Transparent epoxy resin package

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	3	V
Forward current	$I_F$	50	mA
Pulse forward current *	$I_{FP}$	1.5	A
Power dissipation	$P_D$	75	mW
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*:  $f = 100 \text{ Hz}$ , Duty Cycle = Less than 0.1%



### ■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

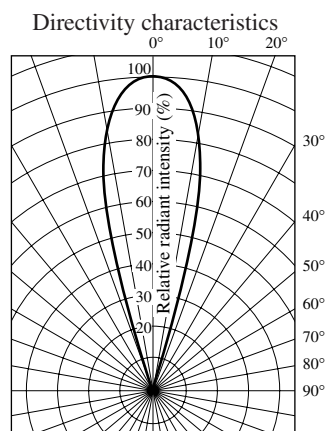
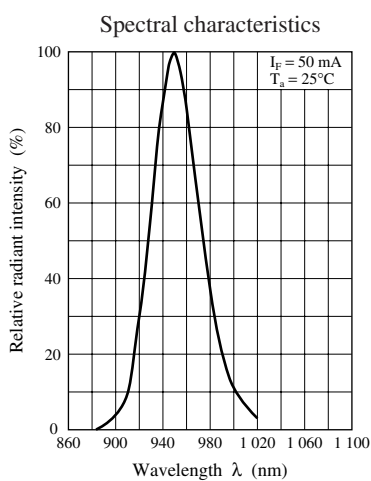
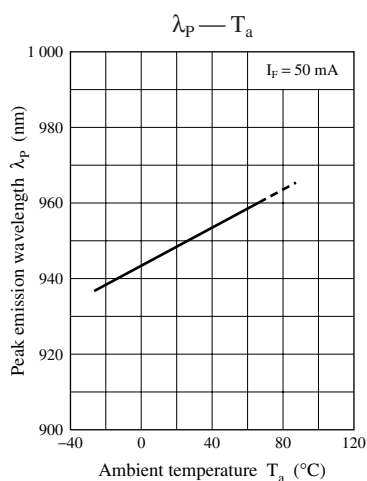
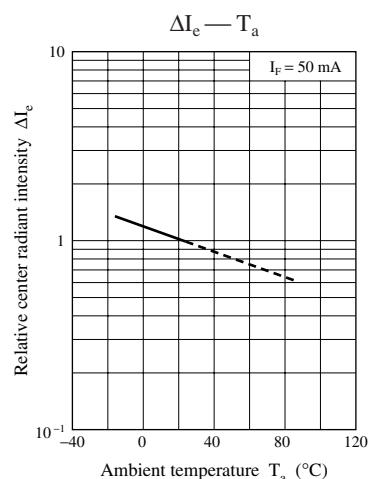
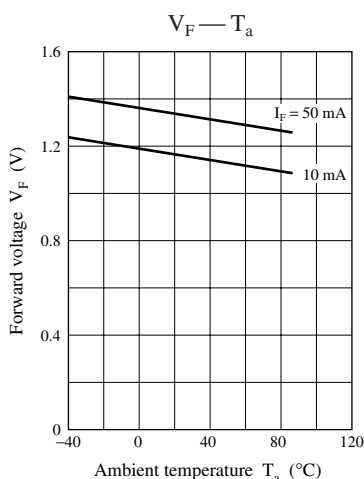
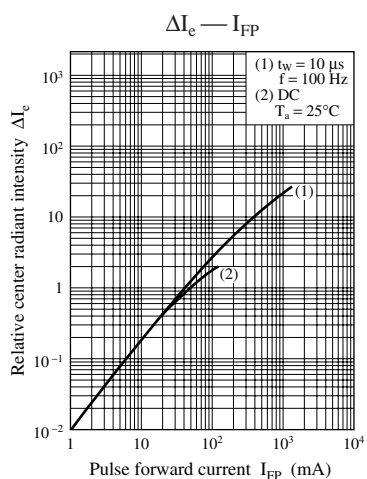
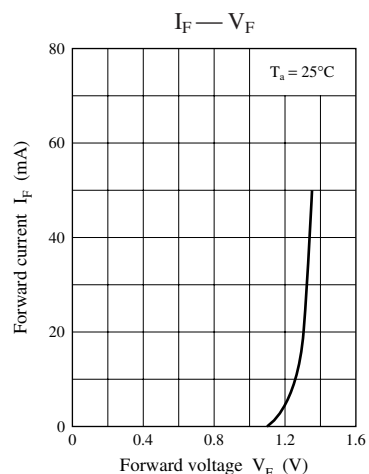
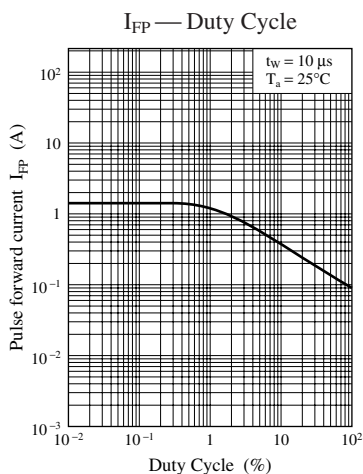
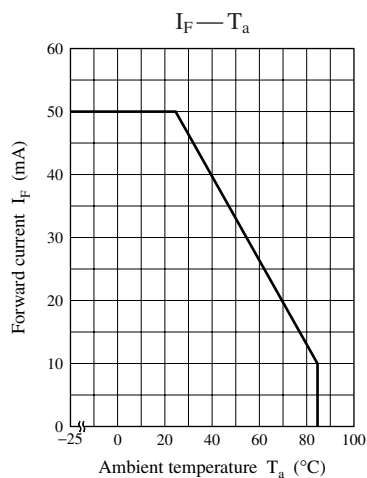
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 50 \text{ mA}$		1.35	1.50	V
Pulse forward voltage *	$V_{FP}$	$I_{FP} = 1.0 \text{ A}$			3.0	V
Reverse current	$I_R$	$V_R = 3 \text{ V}$			10	$\mu\text{A}$
Center radiant intensity	$I_e$	$I_F = 50 \text{ mA}$	13.0			mW/sr
Peak emission wavelength	$\lambda_p$	$I_F = 50 \text{ mA}$		950		nm
Spectral half band width	$\Delta\lambda$	$I_F = 50 \text{ mA}$		50		nm
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}$ , $f = 1 \text{ MHz}$		20		pF
Half-power angle	$\theta$	The angle when the radiant power is halved		15		$^\circ$

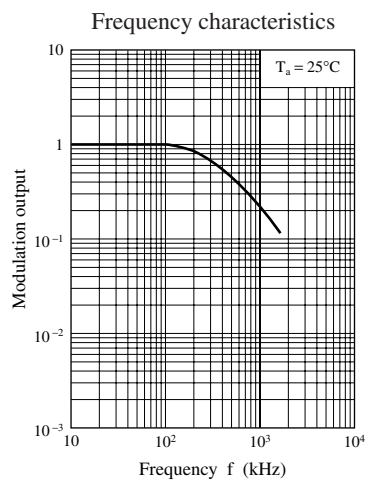
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz

$$f_c: 10 \times \log \frac{P_O \text{ at } f = f_c}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

3. \*:  $f = 100 \text{ Hz}$ , Duty Cycle = Less than 0.1%





# Caution for Safety

 **DANGER**

## ■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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